

FAX COVER SHEET

TO	Examiner Paul Brock
COMPANY	PTO TC2800
FAX NUMBER	17037463915
FROM	Erik Nordstrom
DATE	2003-08-26 20:28:34 GMT
RE	10/092,104 - Proposed Amendment

COVER MESSAGE

Pursuant to our t/c yesterday, attached please find a couple of proposed amendments to overcome the cited references and in particular, Hikita. I look forward to discussing this with you tomorrow morning at 10:00 AM (EST). Thanks, --Erik

2841 TC2800 LDRC Team 1
CP4-3C24

8/29-

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Note that the proposed amendments for overcoming the cited references are not italicized, while the italicized amendments are for the 112(2) objections/rejections. (I don't think we need to address these latter changes.)

*module
benefit*

First Proposed Change

These changes relate to the fact that Hkita does not teach "solder connections" but instead only teaches connections with an-isotropic film.

1. (Amended) A method of creating a stack of integrated circuits selectively connected to provide increased memory density in an application, the method comprising the steps of:

providing a carrier frame configured to have a plurality of members emergent into a window within the carrier frame;

applying a first portion of a solder-containing compound to the first side of the plurality of members;

placing a first packaged integrated circuit ~~in contact with~~ on the plurality of members in contact with the applied solder-containing compound;

processing the first integrated circuit and the carrier frame with a heat source to create a first set of solder connections between the plurality of members and the first packaged integrated circuit;

applying a second portion of the solder-containing compound to the second side of the plurality of members of the carrier frame;

placing a second packaged integrated circuit ~~in contact with~~ on the plurality of members in contact with the second portion of solder-containing compound;

NO Hkita
simultaneously
sequentially

*sealing w/
external
off the end*

processing the second integrated circuit and the carrier frame with a heat source to create a second set of solder connections between the plurality of members and the second integrated circuit.

Second Proposed Change

These amendments relate to the fact that Hikita only teaches stacking IC dies but not stacking "packaged" chips, which is done by solder-connecting their "external" chip leads to the frame member contacts.

1. (Amended) A method of creating a stack of integrated circuits selectively connected to provide increased memory density in an application, the method comprising the steps of:

providing a carrier frame ¹² configured to have a plurality of members ^{12A} emergent into a window within the carrier frame;

applying a first portion of a solder-containing compound to the first side of the plurality of members;

placing a first packaged integrated circuit having external leads ^{16a} in contact with the plurality of members;

processing the first integrated circuit and the carrier frame with a heat source to create a first set of solder connections between the plurality of members and a plurality of the external leads of the first packaged integrated circuit;

applying a second portion of the solder-containing compound to the second side of the plurality of members of the carrier frame;

placing a second packaged integrated circuit having external leads ^{14a} in contact with the plurality of members;

Steps need to be separated

processing the second integrated circuit and the carrier frame with a heat source to create a second set of solder connections between the plurality of members and a plurality of the external leads of the second integrated circuit.